

		<b>Material Composition Declaration</b> Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.						
1752-2 1.1		IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>		<b>Form Type *</b> <b>Distribute</b>		<b>Declaration Class *</b> <b>Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information</b>				
<b>Supplier Information</b>										
<b>Company Name *</b> <b>National Semiconductor</b>		Company Unique ID NATSEMI		Unique ID Authority 04-147-2986		Response Date * 11-11-2011		Response Document ID		
Contact Name * Lorena Dudman		Title - Contact Product Stewardship Eng.		Phone - Contact * 1-408-721-8180		Email - Contact * Green.Project@nsc.com				
Authorized Representative * Lorena Dudman		Title - Representative Product Stewardship Eng.		Phone - Representative * 1-408-721-8180		Email - Representative * Green.Project@nsc.com		Supplier Comments or URL for Additional Information <a href="http://www.national.com/analog/quality/green">http://www.national.com/analog/quality/green</a>		
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type	
		LMX2433SLEX NOPB	LMX2433SLEX NOPB	11-11-2011			17.82	mg	Each	
	Alternate Recommendation				Alternate Item Comments					
<b>Manufacturing Process Information</b>										
Terminal Plating / Grid Array Material <b>NiAu</b>		Terminal Base Alloy <b>Not Applicable</b>		J-STD-020 MSL Rating <b>1</b>		Peak Process Body Temperature <b>260 C</b>		Max Time at Peak Temperature <b>40 seconds</b>		Number of Reflow Cycles <b>4</b>
<b>Comments</b> <b>"Does not contain PFOS."</b>										

<b>RoHS Material Type Declaration</b>	<b>Declaration Type * Custom</b>
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<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium</b>
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Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

1. National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 7(a) or 7(c)-I.
2. National products do not contain and are not manufactured with ozone depleting compounds.
3. National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. National also complies with use restrictions as stipulated in Annex XVII of REACH.
4. National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
5. National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. National's Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION

<b>RoHS Declaration *</b> 1 - Item(s) does not contain RoHS restricted substances per the definition above	<b>Supplier Acceptance *</b>	<b>Accepted</b>
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**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration and above and choose all applicable exemptions.

<b>Declaration Signature</b>
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<b>Supplier Signature</b>	 John L. Conn Vice President Quality	<b>John L. Conn Vice President Quality</b>
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## Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance	PPM
	Plastic	8.709	mg	Requester		SiO2	60676-86-0		7.708	mg		885,000
				Requester		Epoxy Resin	25928-94-3		0.740	mg		85,000
				Requester		Mg(OH)2	1309-42-8		0.261	mg		30,000
	Substrate	7.250	mg	Requester		Cu	7440-50-8		3.074	mg		424,000
				Requester		BT	N/A		2.205	mg		304,200
				Requester		Solder Mask	N/A		1.412	mg		194,700
				Requester		Ni	7440-02-0		0.481	mg		66,300
				Requester		Au	7440-57-5		0.078	mg		10,800
	Chip	1.200	mg	Requester		Si	7440-21-3		1.193	mg		994,000
				Requester		Al	7429-90-5		0.007	mg		6,000
	Wires	0.400	mg	Requester		Au	7440-57-5		0.400	mg		1,000,000
	Die Attach	0.260	mg	Requester		Ag	7440-22-4		0.195	mg		750,000
				Requester		Bismaleimide (resin)	13676-54-5		0.065	mg		250,000